

# Bill of Materials

TI DESIGNS

TIDEP0034

Item	Qty	Reference	Part Description	Manufacturer	Manufacturer Part Number	PCB Footprint
1	3	ADC_TEMP1, OR_T1, OR_T2	LED, Red, SMD	Lite-On	LTST-C170KRKT	LED_LTST-C170
2	20	C272, C273, C274, C275, C276, C277, C278, C279, C443, C445, C446, C447, C448, C449, C450, C451, C452, C453, C454, C455	CAP, CERM, 0.1 µF, 10 V, +/- 10%, X5R, 0201	Samsung	CL03A104KP3NNNC	0201L
3	22	C325, C326, C347, C348, C349, C350, C370, C372, C381, C383, C387, C400, C404, C409, C411, C416, C418, C424, C429, C431, C438, C440	CAP, CERM, 1µF, 10V, +/-10%, X5R, 0603	TDK	C1608X5R1A105K	0603L
4	58	C342, C343, C344, C345, C351, C352, C353, C354, C355, C356, C357, C367, C368, C374, C375, C376, C377, C378, C379, C385, C386, C389, C390, C391, C392, C393, C394, C395, C396, C397, C398, C399, C402, C403, C406, C407, C413, C414, C426, C427, C433, C434, C435, C436	CAP, CERM, 0.1µF, 6.3V, X5R, 10%, 0201	TDK	C0603X5R0J104K	0201
5	14	C335, C346, C358, C362, C373, C384, C388, C401, C405, C412, C419, C425, C432, C441	CAP, TANT, 10µF, 10V, +/-20%, 2.5 ohm, 3528-21 SMD	Vishay-Sprague	293D106X0010B2TE3	3528-21
6	34	C339, C360, C513, C514, C515, C516, C517, C519, C520, C521, C522, C523, C524, C525, C526, C527, C528, C529, C530, C531, C532, C533, C534, C535, C536, C537, C538, C539, C540, C541, C542, C545, C546, C548	CAP, CERM, 0.1µF, 10V, +/-10%, X5R, 0402	TDK	C1005X5R1A104K	0402L
7	1	C361	CAP, CERM, 4.7µF, 6.3V, +/-20%, X5R, 0402	TDK	C1005X5R0J475M050BC	0402L
8	1	C363	CAP, CERM, 0.1µF, 16V, +/-5%, X7R, 0603	AVX	0603YC104JAT2A	0603L
9	3	C364, C365, C366	CAP, CERM, 100pF, 50V, +/-5%, COG/NPO, 0603	AVX	06035A101JAT2A	0603L
10	16	C369, C371, C380, C382, C408, C410, C415, C417, C420, C421, C422, C423, C428, C430, C437, C439	CAP, CERM, 0.01 µF, 6.3 V, +/- 10%, X5R, 0201	TDK	C0603X5R0J103K	0201
11	1	C442	CAP, CERM, 1000 pF, 25 V, +/- 5%, COG/NPO, 0402	TDK	C1005COG1E102J	0402
12	2	C444, C456	CAP, CERM, 0.1 µF, 6.3 V, +/- 10%, X5R, 0402	TDK	C1005X5R0J104K	0402
13	2	C512, C549	CAP, CERM, 1µF, 16V, +/-10%, X5R, 0603	TDK	C1608X5R1C105K	0603L
14	1	C518	CAP, CERM, 0.01µF, 16V, +/-10%, X7R, 0402	TDK	C1005X7R1C103K	0402L
15	2	C543, C550	CAP, CERM, 3900pF, 25V, +/-5%, COG/NPO, 0603	TDK	C1608COG1E392J	0603L
16	2	C544, C551	CAP, CERM, 47pF, 50V, +/-5%, COG/NPO, 0603	AVX	06035A470JAT2A	0603L
17	1	C547	CAP, CERM, 10µF, 10V, +/-10%, X5R, 0805	Kemet	C0805C106K8PACTU	0805L
18	7	L13, L14, L15, L16, L17, L18, L19	Ferrite Bead, 120 ohm @ 100 MHz, 0.55 A, 0402	MuRata	BLM15AG121SN1D	0402
19	12	L20, L21, L22, L23, L24, L25, L26, L27, L28, L29, L30, L31	1.5A Ferrite Bead, 330 ohm @ 100MHz, SMD	MuRata	BLM18SG331TN1D	0603
20	2	Q1, Q2	MOSFET, N/P-CH, 30 V, 1.5 A, 1.0x0.35x0.6mm	Texas Instruments	CSD17483F4T	YJC0003A
21	3	R15, R16, R94	RES, 4.75 k, 1%, 0.063 W, 0402	Vishay-Dale	CRCW04024K75FKED	0402
22	10	R17, R18, R19, R20, R21, R22, R83, R100, R151, R152	RES, 10.0, 1%, 0.063 W, 0402	Vishay-Dale	CRCW040210R0FKED	0402
23	2	R41, R42	RES, 3.0 k, 5%, 0.063 W, 0402	Vishay-Dale	CRCW04023K00JNED	0402
24	12	R76, R77, R78, R80, R81, R82, R90, R91, R92, R98, R101, R102	RES, 10.0k ohm, 1%, 0.1W, 0603	Vishay-Dale	CRCW060310K0FKEA	0603L
25	1	R79	RES, 3.30k ohm, 0.1%, 0.1W, 0603	Susumu Co Ltd	RG1608P-332-B-T5	0603L
26	4	R84, R85, R97, R103	RES, 0, 5%, 0.063 W, 0402	Panasonic	ERJ-2GE0R00X	0402
27	2	R86, R87	RES, 49.9, 1%, 0.063 W, 0402	Vishay-Dale	CRCW040249R9FKED	0402
28	3	R88, R89, R150	RES, 1.3k ohm, 5%, 0.1W, 0603	Yageo America	RC0603JR-071K3L	0603L
29	1	R93	RES, 750 ohm, 5%, 0.1W, 0603	Yageo America	RC0603JR-07750RL	0603L
30	2	R95, R96	RES, 1.00 k, 1%, 0.063 W, 0402	Vishay-Dale	CRCW04021K00FKED	0402
31	1	R99	RES, 1.91 k, 1%, 0.063 W, 0402	Vishay-Dale	CRCW04021K91FKED	0402
32	2	R147, R154	RES, 270 ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW0603270RJNEA	0603L
33	1	R148	RES, 2.32k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-072K32L	0603L
34	2	R149, R153	RES, 619 ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-07619RL	0603L

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35	4	R155, R156, R157, R158	RES, 240, 5%, 0.063 W, 0402	Vishay-Dale	CRCW0402240RJNED	0402
36	2	Status1, Status2	LED, Green, SMD	Lite-On	LTST-C190GKT	LED_LTST-C190
37	1	U1	Smallcell Baseband Processor with 4 C66x DSP Cores / 2 ARM A15 Cores / JESD / CPRI...etc	Texas Instruments	66AK2L06	S-PBGA-N900
38	1	U3	ADC12J4000RLY Ultra-Wideband RF Sampling Subsystem, RLY0068A	Texas Instruments	ADC12J4000NKE	RLY0068A
39	1	U4	Dual Remote Diode and Local Temperature Sensor with SMBus Interface and TruTherm Technology, 14-pin LLP, Pb-Free	National Semiconductor	LM95233CISD/NOPB	SDA14B
40	1	U5	DAC38J84 Quad-Channel, 16-Bit, 1.6/2.5 GSPS, Digital-to-Analog Converters with 12.5 Gbps JESD204B Interface	Texas Instruments	DAC38J84	S-PBGA-N144
41	1	U11	Low-Noise Clock Jitter Cleaner with Dual Loop PLLs, NKD0064A	Texas Instruments	LMK04828BISQ/NOPB	NKD0064A
42	1	U12	High Stability Standard TCXO	Rakon	IT2100F	IT2100F

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